

Listing of Claims:

1-8. (Canceled)

9. (Previously Presented) A method of conveying a substrate from a first base including a first substrate holding mechanism to a second base including a second substrate holding mechanism using a conveyor including a third substrate holding mechanism, the method comprising:

the conveyor attaching the third substrate holding mechanism including an electrostatic chuck to the substrate with the first substrate holding mechanism holding the substrate;

driving the third substrate holding mechanism so that the substrate is transferred from the first substrate holding mechanism to the third substrate holding mechanism to be held thereon by the electrostatic chuck attracting the substrate while the substrate is placed on the first base;

the conveyor conveying the substrate from the first base to the second base and attaching the substrate to the second substrate holding mechanism; and

driving the second substrate holding mechanism so that the substrate is transferred from the third substrate holding mechanism to the second substrate holding mechanism to be held thereon by the second base while the third substrate holding mechanism is attached to the substrate,

wherein each of the first, second and third substrate holding mechanisms includes a surface on which the substrate is held; and

the surface of the third substrate holding mechanism is face-to-face with the surface of the first substrate holding mechanism when the substrate is transferred from the first substrate holding mechanism to the third substrate holding mechanism, and

the surface of the third substrate holding mechanism is face-to-face with the surface of the second substrate holding mechanism when the substrate is transferred from the third substrate holding mechanism to the second substrate holding mechanism.

10. (Canceled)

11. (Original) The method of conveying the substrate as claimed in claim 9, wherein the substrate is held by the first substrate holding mechanism after being subjected to backgrinding.

12. (Previously Presented) The method of conveying the substrate as claimed in claim 9, wherein:

at least one of the first and second bases and the conveyor are provided in reduced pressure chambers, and the substrate holding mechanism provided to the base provided in the reduced pressure chamber is an electrostatic chuck.

13. (Original) The method of conveying the substrate as claimed in claim 12, wherein:

in transferring the substrate between the substrate holding mechanism provided to the base provided in the reduced pressure chamber and the third substrate holding mechanism, voltage is applied to the electrostatic chuck from which the substrate is transferred so that an electrostatic force is generated in a direction to separate the substrate therefrom.